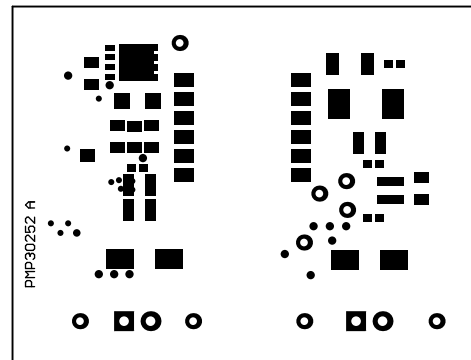
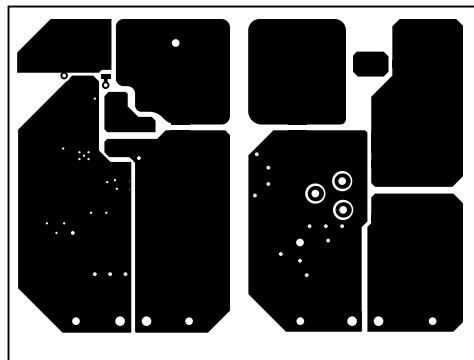


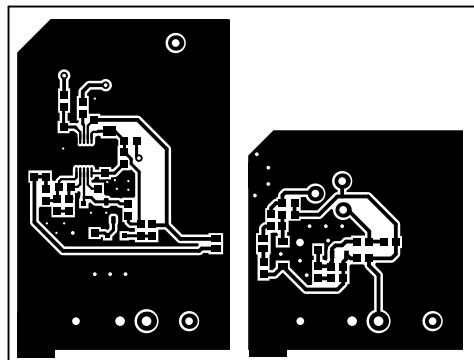
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30252	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #:		
PLOT NAME = Top Overlay	GENERATED : 8/21/2017 14:54:40	TEXAS INSTRUMENTS	



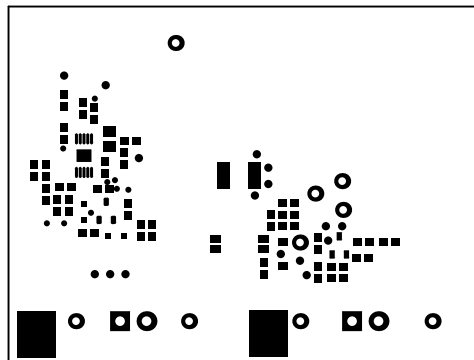
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30252	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #:		
PLOT NAME = Top Solder Mask	GENERATED : 8/21/2017 14:54:41	TEXAS INSTRUMENTS	



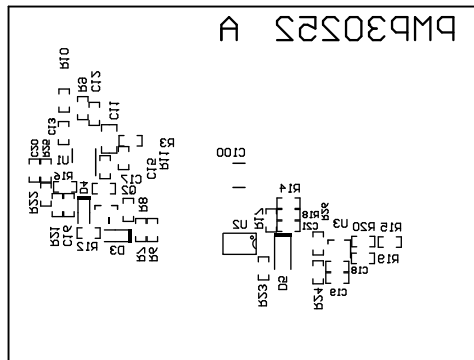
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30252	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #:		
PLOT NAME = Top Layer	GENERATED : 8/21/2017 14:54:41	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30252	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #:		
PLOT NAME = Bottom Layer	GENERATED : 8/21/2017 14:54:42	TEXAS INSTRUMENTS	

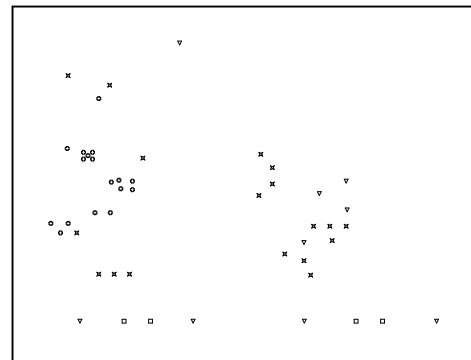


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30252	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #:		
PLOT NAME = Bottom Solder Mask	GENERATED : 8/21/2017 14:54:43	TEXAS INSTRUMENTS	

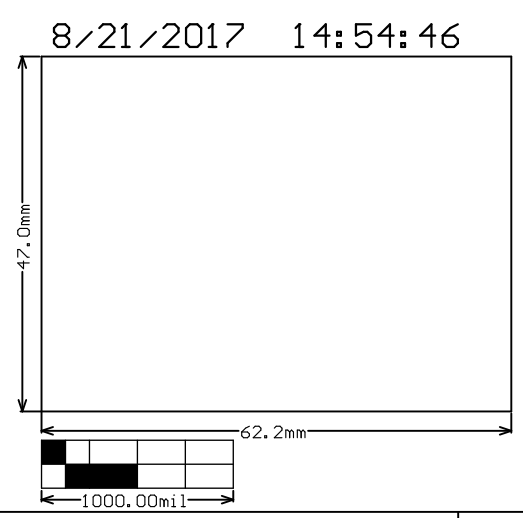


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30252	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #:		
PLOT NAME = Bottom Overlay	GENERATED : 8/21/2017 14:54:44	TEXAS INSTRUMENTS	

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Tolerance
⊗	17	11.81mil (0.300mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	18	19.69mil (0.500mm)	PTH	Round	Top Layer - Bottom Layer	
▽	9	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
□	4	50.00mil (1.270mm)	PTH	Round	Top Layer - Bottom Layer	
	48 Total					



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30252	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #:		
PLOT NAME = Drill Drawing	GENERATED : 8/21/2017 14:54:45	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30252	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #:		
PLOT NAME = Board Dimensions	GENERATED : 8/21/2017 14:54:46	TEXAS INSTRUMENTS	

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